

Part Number: XPC2LUG11D

Top LED

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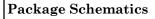
N ø0.9x4

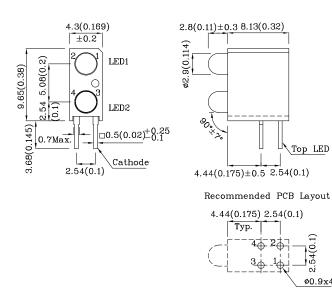
3mm Two Position CBI Housing

Features

- Housing material: Type 66 Nylon
- Black casing provides superior contrast
- Housing UL rating: 94V-0
- Reliable & robust
- Custom color combinations available
- RoHS Compliant







Notes: 1. All dimensions are in millimeters (inches).

2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.

3. Specifications are subject to change without notice.

Absolute Maximum Ratings T _A =25°C)		Green (GaP)	Unit			
Reverse Voltage	VR	5	V			
Forward Current	$I_{\rm F}$	25	mA			
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	140	mA			
Power Dissipation	PD	62.5	mW			
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C			
Storage Temperature	Tstg	-40 ~ +85				
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds					
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds					

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

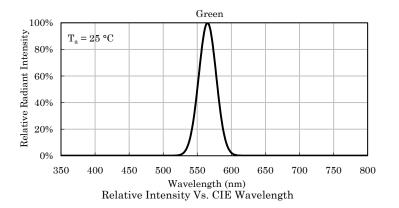
Operating Characteristics (T _A =25°C)	Green (GaP)	Unit	
Forward Voltage (Typ.) (I _F =10mA)	$V_{\rm F}$	2	V
Forward Voltage (Max.) (I _F =10mA)	$V_{\rm F}$	2.4	V
Reverse Current (Max.) (V _R =5V)	I_R	10	μΑ
Wavelength of Peak Emission CIE127-2007*(Typ.) (I _F =10mA)	λP	565*	nm
Wavelength of Dominant Emission CIE127-2007*(Typ.) (I _F =10mA)	λD	568*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	$ riangle \lambda$	30	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	pF

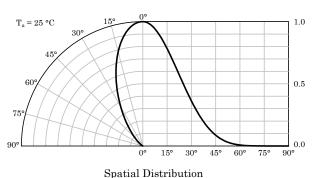
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (I _F =10mA) mcd		Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XPC2LUG11D	Green	GaP	Green Diffused	10*	24*	565*	50°

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

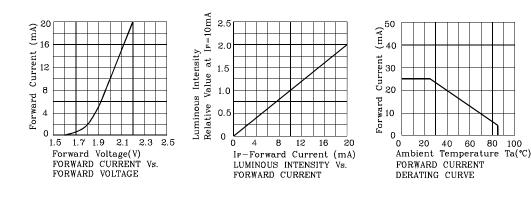


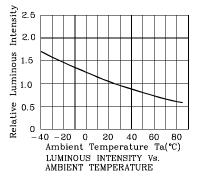
3mm Two Position CBI Housing



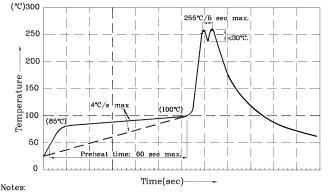


Green





Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



Notes: 1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C 2. Peak wave soldering temperature between 245°C \sim 255°C for 3 sec (5. cm max)

(5 sec max).

3.Do not apply stress to the epoxy resin while the temperature is above 85°C. 4.Fixtures should not incur stress on the component when mounting and during soldering process. 5.SAC 305 solder alloy is recommended. 6.No more than one wave soldering pass.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

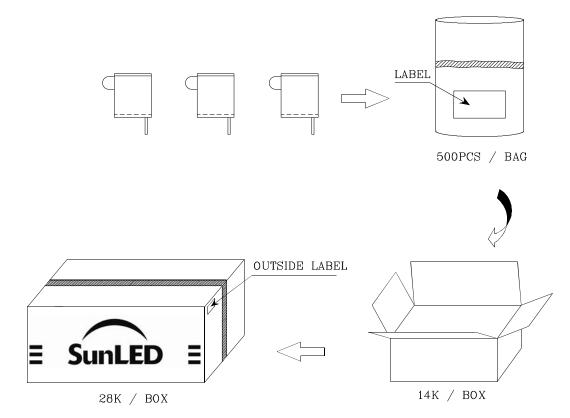
the typical accuracy of the sorting process is as follows:

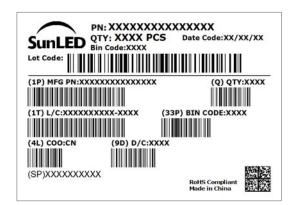
- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS





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